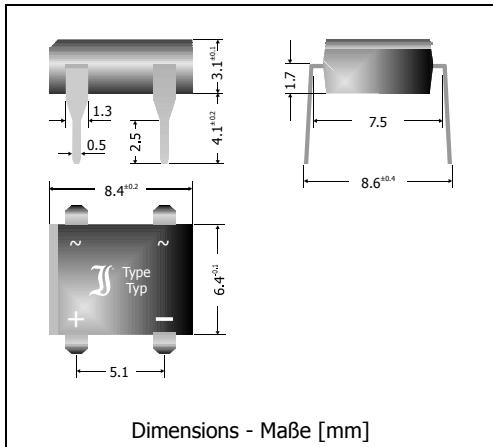


CS10D ... CS50D
Schottky-Bridge-Rectifiers
Schottky-Brückengleichrichter

Version 2007-12-03



Nominal current Nennstrom	1 A
Alternating input voltage Eingangswechselspannung	10...50 V
Plastic case DIL Kunststoffgehäuse DIL	8.3 x 6.4 x 3.1 [mm]
Weight approx. – Gewicht ca.	0.4 g
Plastic material has UL classification 94V-0 Gehäusematerial UL94V-0 klassifiziert	
Standard packaging: plastic tubes Standard Lieferform: Plastik-Schienen	



Recognized Product – Underwriters Laboratories Inc.® File E175067
 Anerkanntes Produkt – Underwriters Laboratories Inc.® Nr. E175067

Maximum ratings and characteristics**Grenz- und Kennwerte**

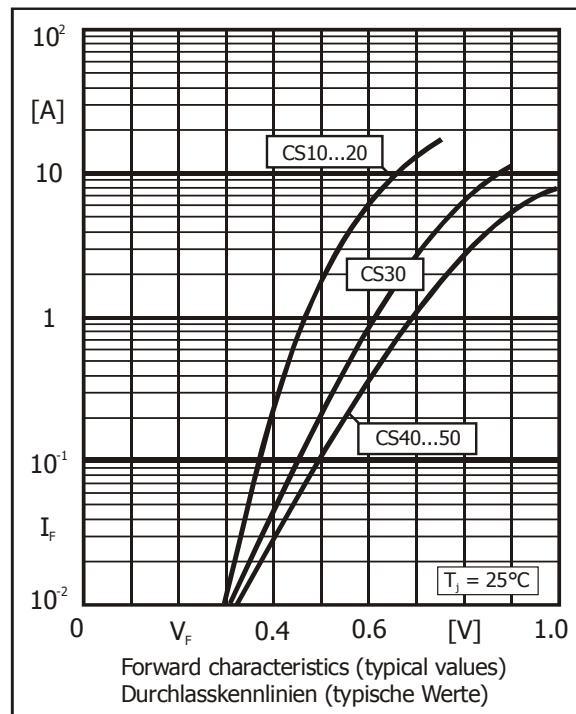
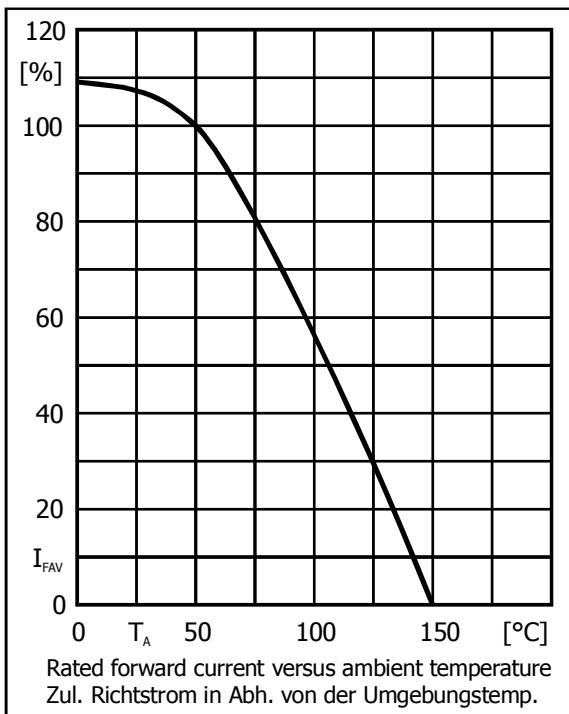
Type Typ	Max. alternating input voltage Max. Eingangswechselspannung V_{VRMS} [V]	Repetitive peak reverse voltage Period. Spitzensperrspannung V_{RRM} [V]	Forward voltage Durchlass-Spannung V_F [V] ^{1,2)}
CS10D	10	20	< 0.50
CS20D	20	40	< 0.50
CS30D	30	60	< 0.70
CS40D	40	80	< 0.79
CS50D	50	100	< 0.79

Repetitive peak forward current Periodischer Spitzenstrom	$f > 15$ Hz	I_{FRM}	10 A ³⁾
Peak forward surge current, 50/60 Hz half sine-wave Stoßstrom für eine 50/60 Hz Sinus-Halbwelle	$T_A = 25^\circ\text{C}$	I_{FSM}	40/44 A
Rating for fusing, $t < 10$ ms Grenzlastintegral, $t < 10$ ms	$T_A = 25^\circ\text{C}$	i^2t	8 A ² s
Operating junction temperature – Sperrschiichttemperatur Storage temperature – Lagerungstemperatur	T_j T_s	-50...+150°C	-50...+150°C

¹ $I_F = 1$ A, $T_j = 25^\circ\text{C}$ ² Per Diode – Pro Diode³ Max. temperature of the terminals $T_T = 100^\circ\text{C}$ – Max. Temperatur der Anschlüsse $T_T = 100^\circ\text{C}$

Characteristics

			Kennwerte
Max. average forward rectified current Dauergrenzstrom	$T_A = 50^\circ\text{C}$	R-load C-load	I_{FAV} $1.0 \text{ A}^1)$ I_{FAV} $0.8 \text{ A}^1)$
Leakage current Sperrstrom	$T_j = 25^\circ\text{C}$ $T_j = 100^\circ\text{C}$	$V_R = V_{RRM}$ $V_R = V_{RRM}$	I_R $< 0.5 \text{ mA}$ I_R $< 5.0 \text{ mA}$
Thermal resistance junction to ambient air Wärmewiderstand Sperrsicht – umgebende Luft			R_{thA} $< 60 \text{ K/W}^1)$



1 Mounted on P.C. Board with 25 mm^2 copper pads at each terminal
Montage auf Leiterplatte mit 25 mm^2 Kupferbelag (Lötpad) an jedem Anschluss